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Kasem et al.

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(54) **SEMICONDUCTOR CHIP PACKAGE**

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(*) Notice: This patent is subject to a terminal disclaimer.

(**) Term: **14 Years**

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(51) **LOC (7) Cl.** **13-03**

(52) **U.S. Cl.** **D13/182**

(58) **Field of Search** D13/110, 182; 174/52.1, 52.2, 52.4, 52.5, 16.3; 206/710, 711, 832; 257/254, 678, 659, 668, 667, 670, 676, 679, 686, 688, 690, 691, 692, 696, 703, 778; 361/679, 728, 742, 752, 802, 818

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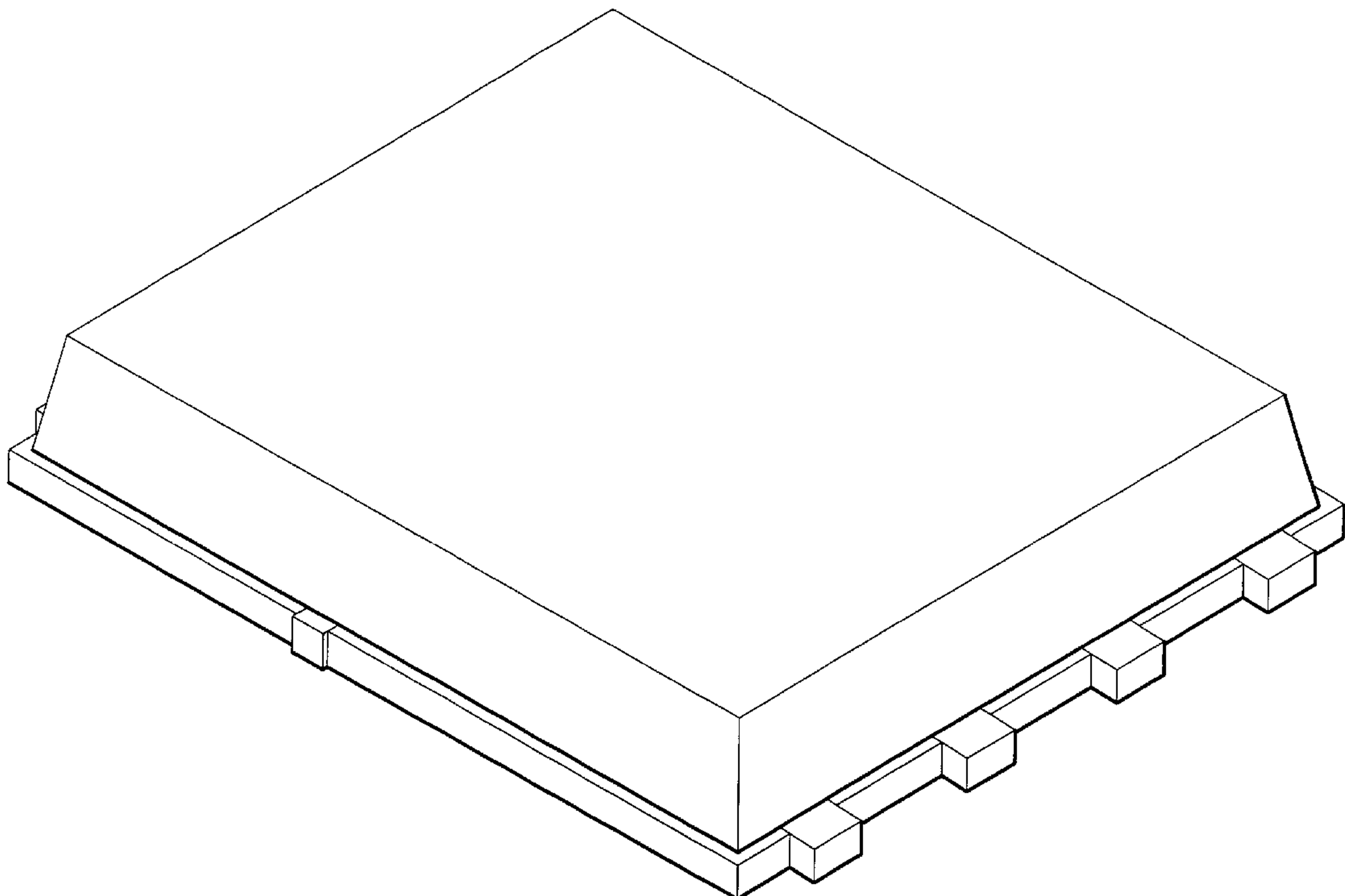
(57) **CLAIM**

The ornamental design for a semiconductor chip package, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view from the left side and above the semiconductor chip package;
 FIG. 2 is a perspective view from the left side and below the semiconductor chip package;
 FIG. 3 is an elevational view from the left side of the semiconductor chip package;
 FIG. 4 is an elevational view from the right side of the semiconductor chip package;
 FIG. 5 is an elevational view from the back side of the semiconductor chip package;
 FIG. 6 is an elevational view from the front side of the semiconductor chip package;
 FIG. 7 is a top view of the semiconductor chip package; and,
 FIG. 8 is a bottom view of the semiconductor chip package.

1 Claim, 8 Drawing Sheets



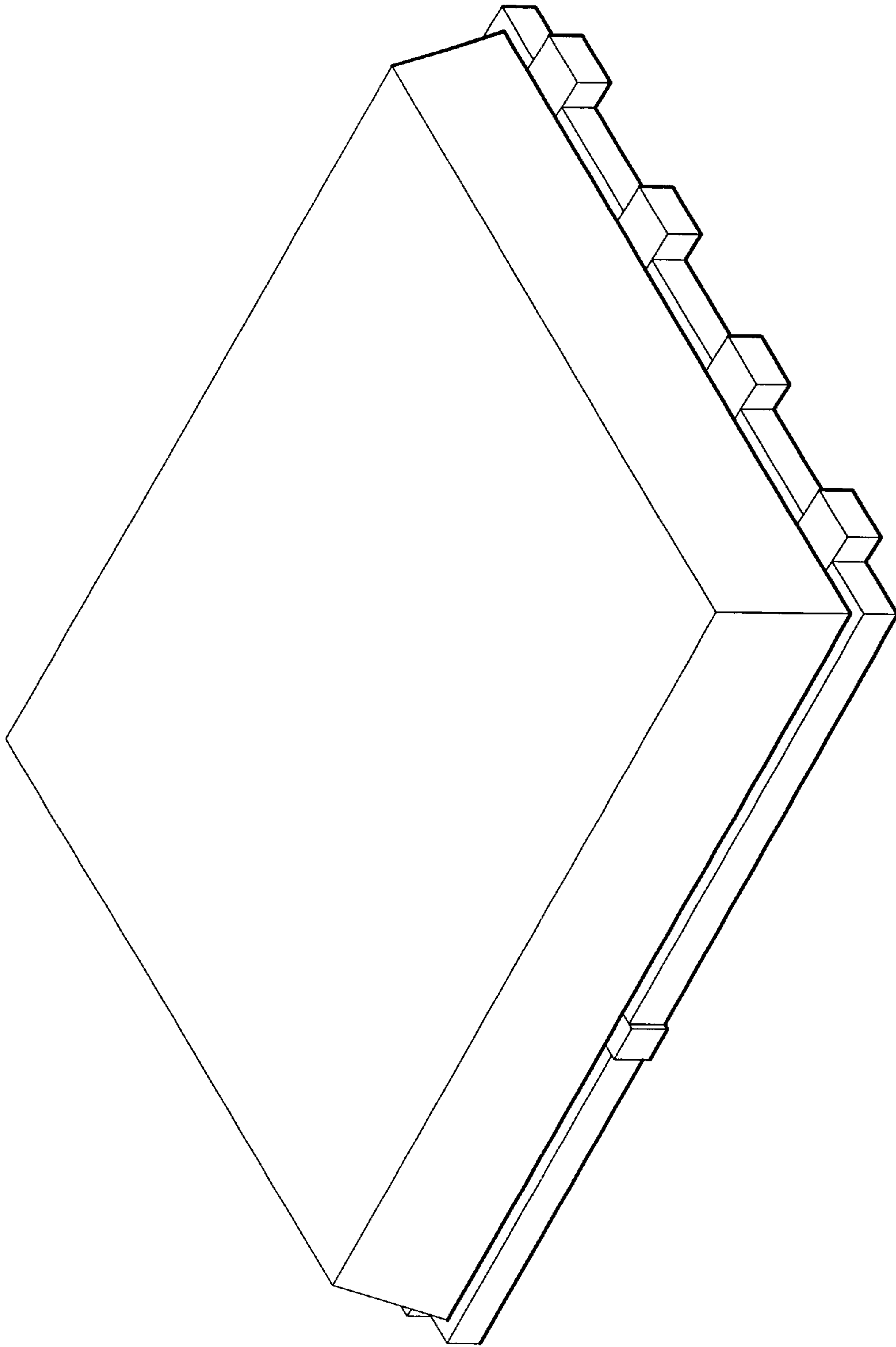


FIG. 1

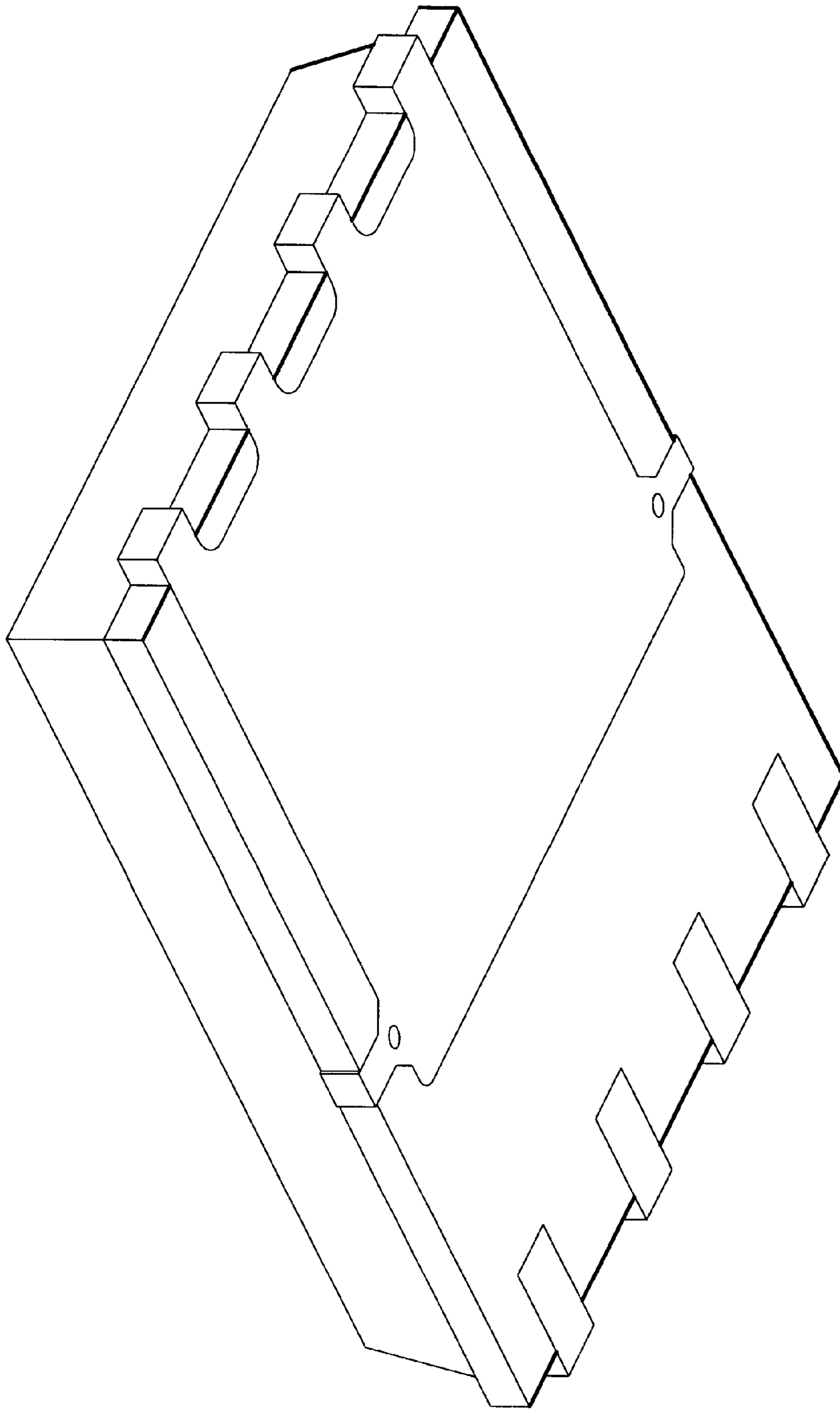


FIG. 2

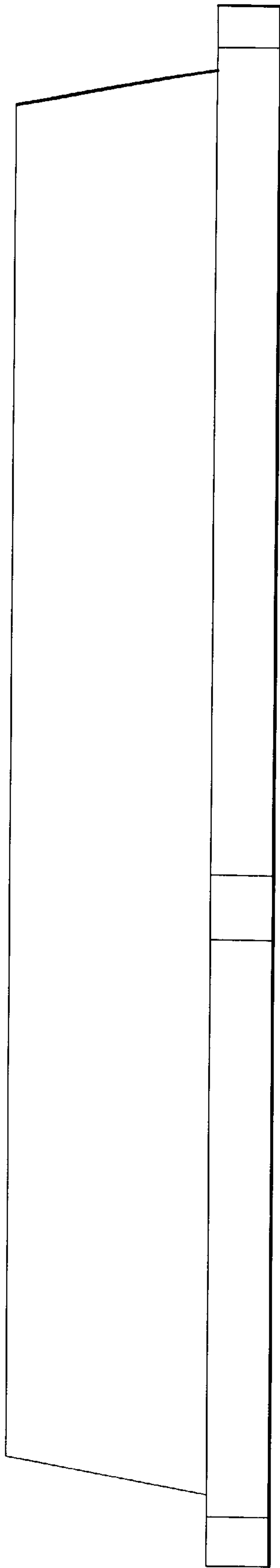


FIG. 3

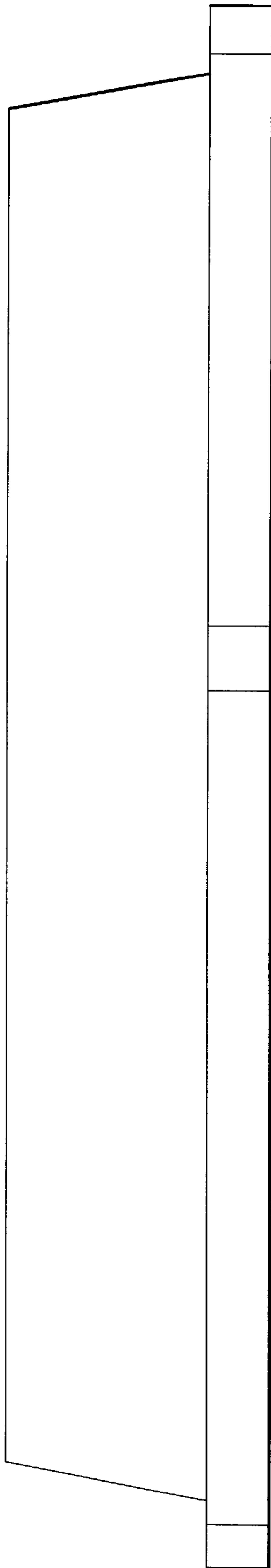


FIG. 4

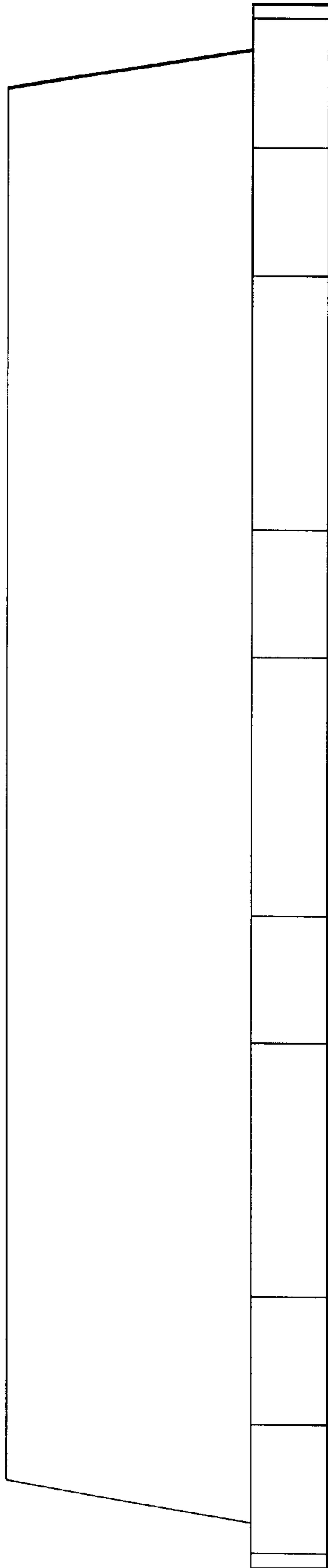


FIG. 5

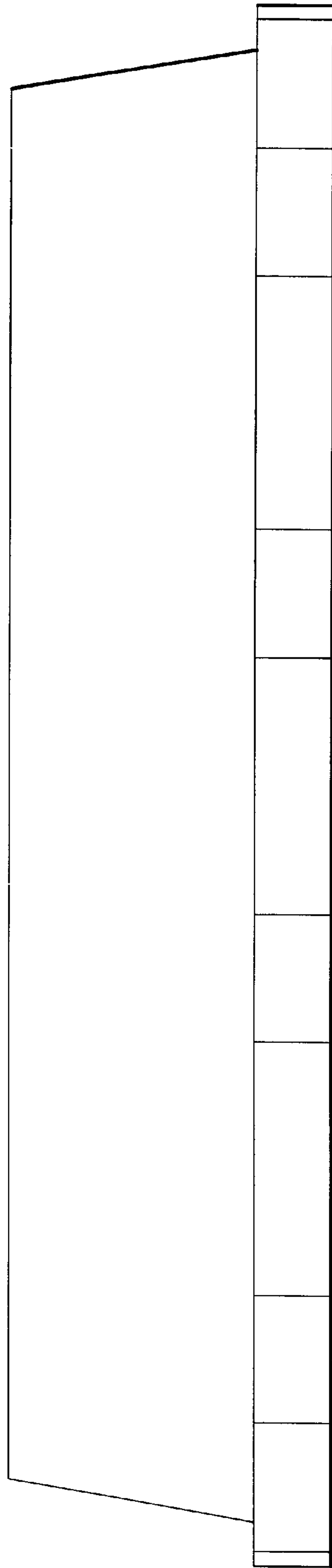


FIG. 6

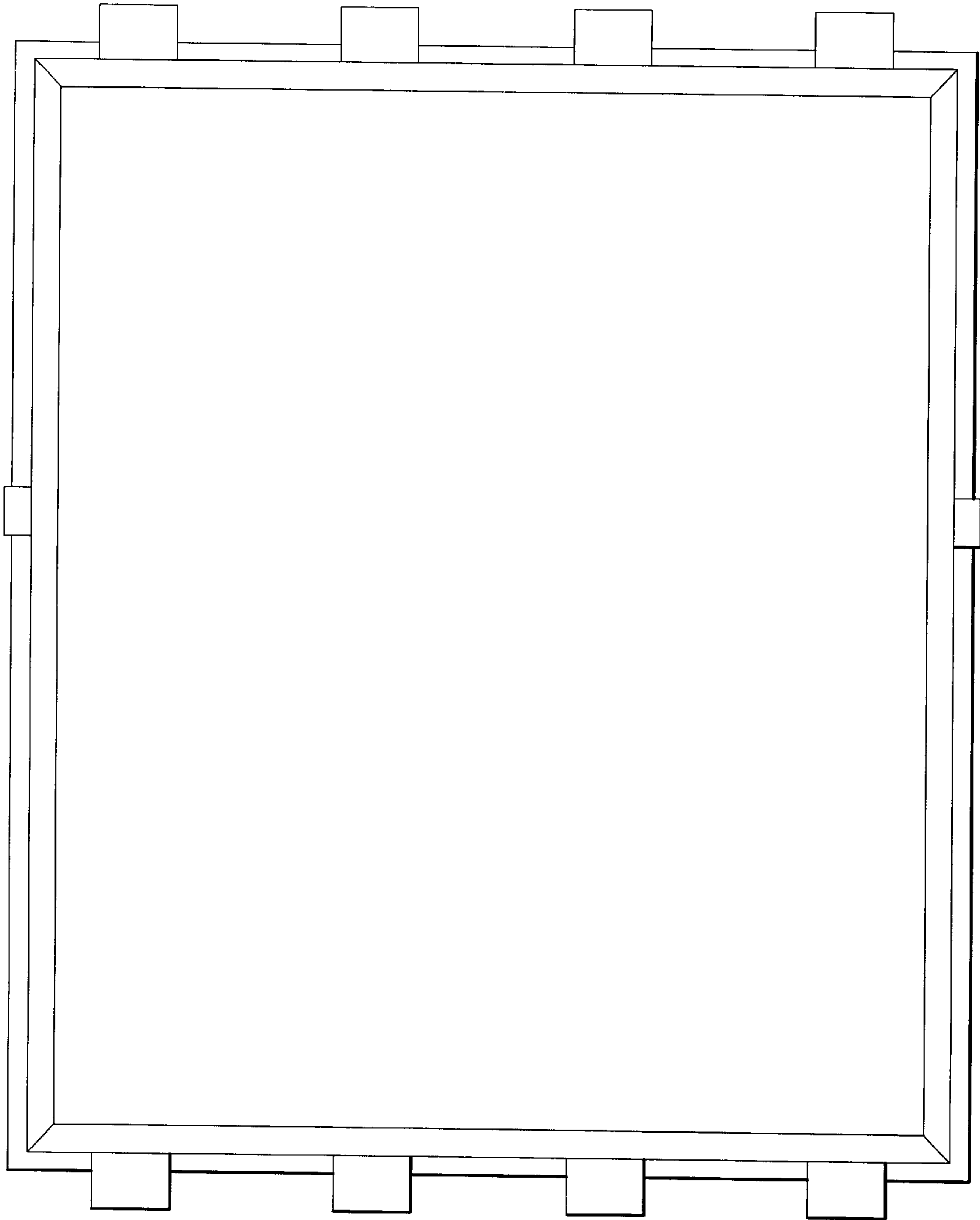


FIG. 7

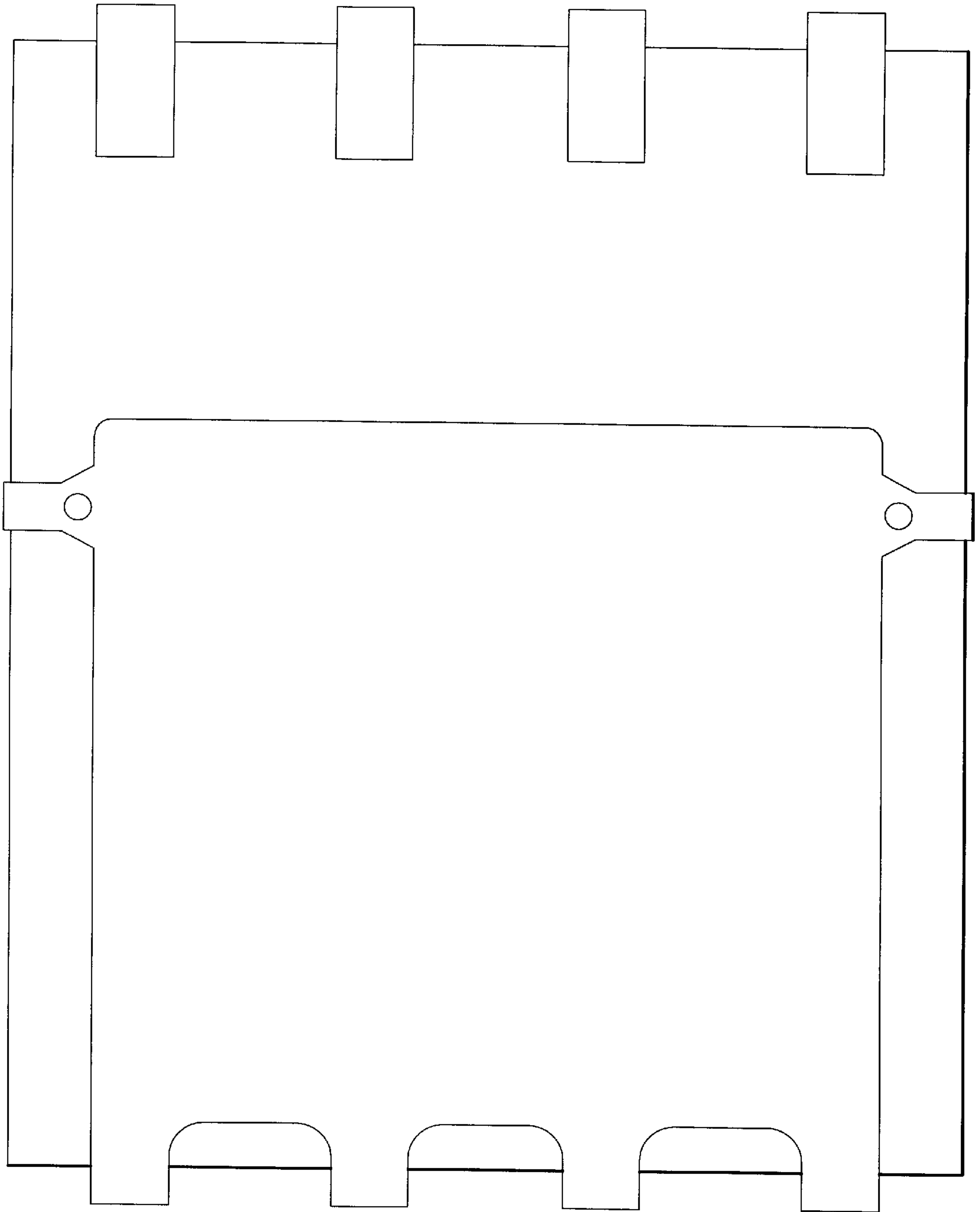


FIG. 8